Distributed by:

JAMECO

ELECTRONICS

www.Jameco.com + 1-800-831-4242

The content and copyrights of the attached material are the property of its owner.

Jameco Part Number 1498015



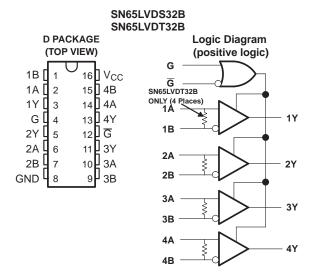
HIGH-SPEED DIFFERENTIAL RECEIVERS

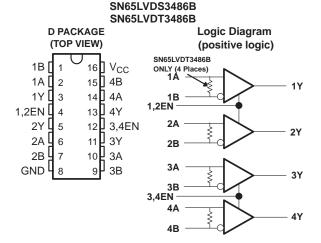
FEATURES

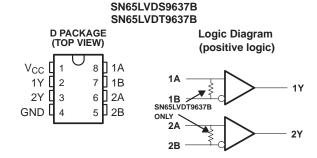
- Meets or Exceeds the Requirements of ANSI EIA/TIA-644 Standard for Signaling Rates (1) up to 400 Mbps
- Operates With a Single 3.3-V Supply
- -2-V to 4.4-V Common-Mode Input Voltage Range
- Differential Input Thresholds <50 mV With 50 mV of Hysteresis Over Entire Common-Mode Input Voltage Range
- Integrated 110- Ω Line Termination Resistors Offered With the LVDT Series
- Propagation Delay Times 4 ns (typ)
- Active Fail Safe Assures a High-Level Output With No Input
- Bus-Pin ESD Protection Exceeds 15 kV HBM
- Inputs Remain High-Impedance on Power Down
- Recommended Maximum Parallel Rate of 200 M-Transfer/s
- Available in Small-Outline Package With 1,27-mm Terminal Pitch
- Pin-Compatible With the AM26LS32, MC3486, or µA9637

DESCRIPTION

This family of differential line receivers offers improved performance and features that implement the electrical characteristics of low-voltage differential signaling (LVDS). LVDS is defined in the TIA/EIA-644 standard. This improved performance represents the second generation of receiver products for this standard, providing a better overall solution for the cabled environment. This generation of products is an extension to TI's overall product portfolio and is not necessarily a replacement for older LVDS receivers.







 Signaling rate, 1/t, where t is the minimum unit interval and is expressed in the units bit/s (bits per second).



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.





These devices have limited built-in ESD protection. The leads should be shorted together or the device placed in conductive foam during storage or handling to prevent electrostatic damage to the MOS gates.

DESCRIPTION (CONTINUED)

Improved features include an input common-mode voltage range 2 V wider than the minimum required by the standard. This will allow longer cable lengths by tripling the allowable ground noise tolerance to 3 V between a driver and receiver. TI has additionally introduced an even wider input common-mode voltage range of –4 to 5 V in their SN65LVDS/T33 and SN65LVDS/T34.

Precise control of the differential input voltage thresholds now allows for inclusion of 50 mV of input voltage hysteresis to improve noise rejection on slowly changing input signals. The input thresholds are still no more than ±50 mV over the full input common-mode voltage range.

The high-speed switching of LVDS signals almost always necessitates the use of a line impedance matching resistor at the receiving-end of the cable or transmission media. The SN65LVDT series of receivers eliminates this external resistor by integrating it with the receiver. The non-terminated SN65LVDS series is also available for multidrop or other termination circuits.

The receivers can withstand ±15-kV human-body model (HBM) and ±600 V-machine model (MM) electrostatic discharges to the receiver input pins with respect to ground without damage. This provides reliability in cabled and other connections where potentially damaging noise is always a threat.

The receivers also include a (patent pending) fail-safe circuit that will provide a high-level output within 600 ns after loss of the input signal. The most common causes of signal loss are disconnected cables, shorted lines, or powered-down transmitters. This prevents noise from being received as valid data under these fault conditions. This feature may also be used for wired-OR bus signaling.

The intended application of these devices and signaling technique is for point-to-point baseband data transmission over controlled impedance media of approximately 100 Ω . The transmission media may be printed-circuit board traces, backplanes, or cables. The ultimate rate and distance of data transfer is dependent upon the attenuation characteristics of the media and the noise coupling to the environment.

The SN65LVDS32B, SN65LVDT32B, SN65LVDS3486B, SN65LVDT3486B, SN65LVDS9637B, and SN65LVDT9637B are characterized for operation from -40°C to 85°C.

AVAILABLE OPTIONS

PART NUMBER ⁽¹⁾	NUMBER OF RECEIVERS	TERMINATION RESISTOR	SYMBOLIZATION
SN65LVDS32BD	4	No	LVDS32B
SN65LVDT32BD	4	Yes	LVDT32B
SN65LVDS3486BD	4	No	LVDS3486
SN65LVDT3486BD	4	Yes	LVDT3486
SN65LVDS9637BD	2	No	DK637B
SN65LVDT9637BD	2	Yes	DR637B

(1) Add the suffix R for taped and reeled carrier.

FUNCTION TABLES

SN65LVDS32B and SN65LVDT32B

DIFFERENTIAL INPUT	ENAB	LES ⁽¹⁾	OUTPUT ⁽¹⁾
A-B	G	G	Υ
$V_{ID} \ge -32 \text{ mV}$	H X	X L	H H
$-100 \text{ mV} < V_{\text{ID}} \le -32 \text{ mV}$	H X	X L	?
V _{ID} ≤ −100 mV	H X	X L	L L
X	L	Н	Z
Open	H X	X L	H H

(1) H = high level, L = low level, X = irrelevant, Z = high impedance (off), ? = indeterminate

SN65LVDS3486B and SN65LVDT3486B

DIFFERENTIAL INPUT	ENABLES ⁽¹⁾	OUTPUT ⁽¹⁾
A-B	EN	Υ
V _{ID} ≥ −32 mV	Н	Н
$-100 \text{ mV} < V_{\text{ID}} \le -32 \text{ mV}$	Н	?
$V_{ID} \le -100 \text{ mV}$	Н	L
X	L	Z
Open	Н	Н

(1) H = high level, L = low level, X = irrelevant, Z = high impedance (off), ? = indeterminate

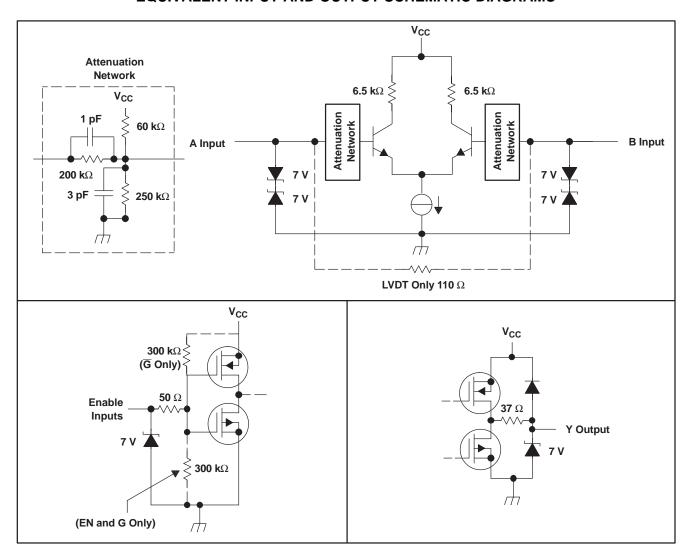
SN65LVDS9637B and SN65LVDT9637B

DIFFERENTIAL INPUT	OUTPUT ⁽¹⁾
A-B	Y
V _{ID} ≥ -32 mV	Н
-100 mV < V _{ID} ≤ -32 mV	?
V _{ID} ≤ -100 mV	L
Open	Н

(1) H = high level, L = low level, ? = indeterminate



EQUIVALENT INPUT AND OUTPUT SCHEMATIC DIAGRAMS





ABSOLUTE MAXIMUM RATINGS

over operating free-air temperature range (unless otherwise noted)(1)

			UNIT
V_{CC}	Supply voltage range(2	2)	-0.5 V to 4 V
	Enables or Y		-0.5 V to V _{CC} + 3 V
	Voltage range	A or B	-4 V to 6 V
		V _A - V _B (LVDT)	1 V
	Electrostatic discharge	A, B, and GND ⁽³⁾	Class 3, A: 15 kV, B: 600 V
	Continuous power diss	sipation	See Dissipation Rating Table
	Storage temperature range		−65°C to 150°C
	Lead temperature 1,6 i	mm (1/16 inch) from case for 10 seconds	260°C

⁽¹⁾ Stresses beyond those listed under absolute maximum ratings may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under recommended operating conditions is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

DISSIPATION RATING TABLE

PACKAGE	T _A ≤ 25°C POWER RATING	OPERATING FACTOR ⁽¹⁾ ABOVE T _A = 25°C	T _A = 85°C POWER RATING	
D8	725 mW	5.8 mW/°C	377 mW	
D16	950 mW	7.6 mW/°C	494 mW	

⁽¹⁾ This is the inverse of the junction-to-ambient thermal resistance when board-mounted and with no air flow.

RECOMMENDED OPERATING CONDITIONS

				MIN	NOM	MAX	UNIT
V _{CC}	Supply voltage			3	3.3	3.6	٧
V _{IH}	High-level input voltage	Enables		2			V
V_{IL}	Low-level input voltage	Enables				8.0	٧
177.1	NA - mitual - of differential in mutual and	LVDS		0.1		3	V
V _{ID}	Magnitude of differential input voltage	LVDT				0.8	٧
V _I or V _{IC}	Voltage at any bus terminal (separately	or common-mode)		-2		4.4	٧
T _A	Operating free-air temperature		-40		85	°C	

⁽²⁾ All voltage values, except differential I/O bus voltages, are with respect to network ground terminal.

⁽³⁾ Tested in accordance with MIL-STD-883C Method 3015.7.



ELECTRICAL CHARACTERISTICS

over recommended operating conditions (unless otherwise noted)

PARAMETER		TEST CONDITIONS	MIN	TYP ⁽¹⁾	MAX	UNIT	
V _{IT1}	Positive-going differential input v	oltage threshold	V _{IB} = -2 V or 4.4 V,			50	
V _{IT2}	Negative-going differential input	voltage threshold	See Figure 1 and Figure 2	-50			mV
V _{IT3}	Differential input fail-safe voltage threshold		See Table 1 and Figure 5	-32		-100	mV
V _{ID(HYS)}	Differential input voltage hysteres	sis, V _{IT1} - V _{IT2}			50		mV
V _{OH}	High-level output voltage		I _{OH} = -4 mA	2.4			V
V _{OL}	Low-level output voltage		I _{OL} = 4 mA			0.4	V
			G or EN at V _{CC} , No load, Steady-state		16	23	
I _{CC}	Supply current	'32B or '3486B	G or EN at GND		1.1	5	mA
		'9637B	No load, Steady-state		8	12	
			V _I = 0 V, Other input open			±20	
		01/05/17/00	V _I = 2.4 V, Other input open	±			
I _I Input current (A or B input	Input ourrest (A or B inpute)	SN65LVDS	V _I = −2 V, Other input open			±40	μA
			V _I = 4.4 V, Other input open			±40	
	Input current (A or B inputs)	SN65LVDT	V _I = 0 V, Other input open	=			
			V _I = 2.4 V, Other input open			±40	
		SINOSLVDI	$V_I = -2 V$, Other input open			±80	μΑ
			V _I = 4.4 V, Other input open			±80	
I _{ID}	Differential input current	SN65LVDS	V_{ID} = 100 mV, V_{IC} = -2 V or 4.4 V, See Figure 1			±3	μΑ
.5	(I _{IA} - I _{IB})	SN65LVDT	$V_{ID} = 0.2 \text{ V}, V_{IC} = -2 \text{ V or } 4.4 \text{ V}$	1.55		2.22	mA
		SN65LVDS	V_A or $V_B = 0$ V or 2.4 V, $V_{CC} = 0$ V			±20	
	Power-off input current	SNOSLVDS	V_A or $V_B = -2 \text{ V}$ or 4.4 V, $V_{CC} = 0 \text{ V}$	±35		±35	
I _{I(OFF)}	(A or B inputs)	SN65LVDT	V_A or $V_B = 0$ V or 2.4 V, $V_{CC} = 0$ V			±30	μΑ
		SINOSLVDI	V_A or $V_B = -2$ V or 4.4 V, $V_{CC} = 0$ V			±50	
I _{IH}	High-level input current (enables)	V _{IH} = 2 V			10	μΑ
I _{IL}	Low-level input current (enables)		V _{IL} = 0.8 V			10	μΑ
l _{OZ}	High-impedance output current					±10	μΑ
Cı	Input capacitance, A or B input to	GND	$V_I = 0.4 \sin (4E6\pi t) + 0.5 V$		5		pF

⁽¹⁾ All typical values are at 25°C and with a 3.3 V supply.



SWITCHING CHARACTERISTICS

over operating free-air temperature range (unless otherwise noted)

	PARAMETER	TEST CONDITIONS	MIN	TYP ⁽¹⁾	MAX	UNIT
t _{PLH}	Propagation delay time, low-to-high-level output	See Figure 3	2.5	4	6	ns
t _{PHL}	Propagation delay time, high-to-low-level output	See Figure 3	2.5	4	6	ns
t _{d1}	Delay time, fail-safe deactivate time	See Figure 3 and			9	ns
t _{d2}	Delay time, fail-safe activate time	Figure 6	0.3		1.5	μs
t _{sk(p)}	Pulse skew (t _{PHL1} - t _{PLH1})			200		ps
t _{sk(o)}	Output skew ⁽²⁾			150		ps
t _{sk(pp)}	Part-to-part skew ⁽³⁾	C _L = 10 pF, See Figure 3			1	ns
t _r	Output signal rise time			0.8		ns
t _f	Output signal fall time			0.8		ns
t _{PHZ}	Propagation delay time, high-level-to-high-impedance output			5.5	9	ns
t_{PLZ}	Propagation delay time, low-level-to-high-impedance output	See Figure 4		4.4	9	ns
t _{PZH}	Propagation delay time, high-impedance -to-high-level output	See Figure 4		3.8	9	ns
t _{PZL}	Propagation delay time, high-impedance-to-low-level output			7	9	ns

- (1) All typical values are at 25°C and with a 3.3-V supply.
 (2) t_{sk(o)} is the magnitude of the time difference between the t_{PLH} or t_{PHL} of all receivers of a single device with all of their inputs driven together.
- $t_{sk(pp)}$ is the magnitude of the time difference in propagation delay times between any specified terminals of two devices when both devices operate with the same supply voltages, at the same temperature, and have identical packages and test circuits.



PARAMETER MEASUREMENT INFORMATION

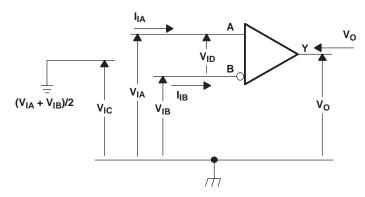
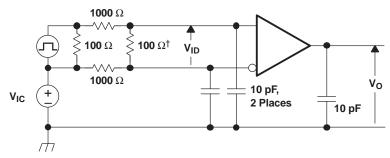
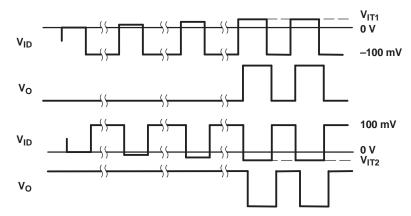


Figure 1. Voltage and Current Definitions



† Removed for testing the LVDT device

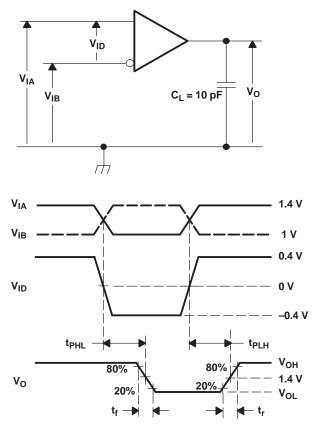


NOTE: Input signal of 3 Mpps, duration of 167 ns, and transition time of <1 ns.

Figure 2. V_{IT1} and V_{IT2} Input Voltage Threshold Test Circuit and Definitions



PARAMETER MEASUREMENT INFORMATION (continued)

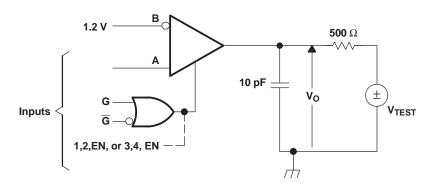


A. All input pulses are supplied by a generator having the following characteristics: t_r or $t_r \le 1$ ns, pulse repetition rate (PRR) = 50 Mpps, Pulsewidth = 10 ±0.2 ns . C_L includes instrumentation and fixture capacitance within 0,06 mm of the D.U.T.

Figure 3. Timing Test Circuit and Waveforms



PARAMETER MEASUREMENT INFORMATION (continued)



NOTE: All input pulses are supplied by a generator having the following characteristics: t_f or $t_f \le 1$ ns, pulse repetition rate (PRR) = 0.5 Mpps, Pulsewidth = 500 ± 10 ns . C_L includes instrumentation and fixture capacitance within 0,06 mm of the D.U.T.

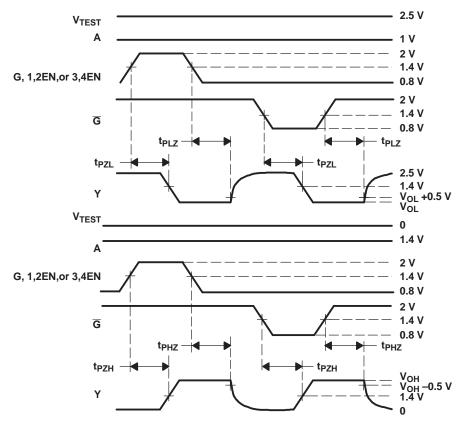


Figure 4. Enable/Disable Time Test Circuit and Waveforms





Table 1. Receiver Minimum and Maximum V _{IT3}	Input Threshold Test Voltages
--	-------------------------------

APPLIED \	OLTAGES ⁽¹⁾	RESULTANT INPUTS			
V _{IA} (mV)	V _{IB} (mV)	V _{ID} (mV)	V _{IC} (mV)	Output	
-2000	-1900	-100	-1950	L	
-2000	-1968	-32	-1984	Н	
4300	4400	-100	4350	L	
4368	4400	-32	4384	Н	

(1) These voltages are applied for a minimum of 1.5 μ s.

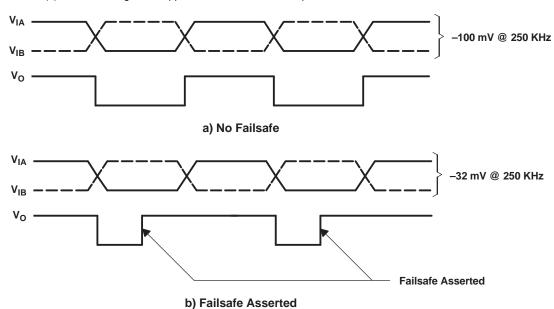


Figure 5. V_{IT3} Failsafe Threshold Test

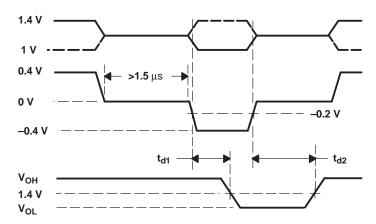
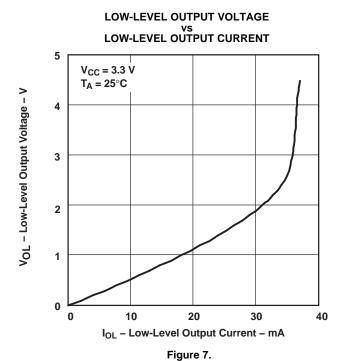
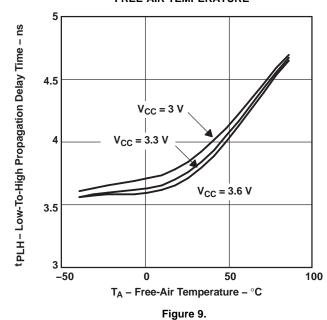


Figure 6. Waveforms for Failsafe Activate and Deactivate

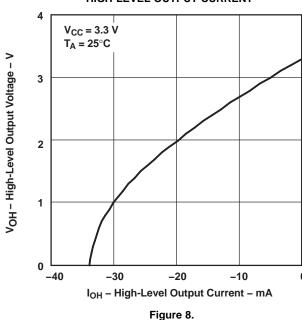
TYPICAL CHARACTERISTICS



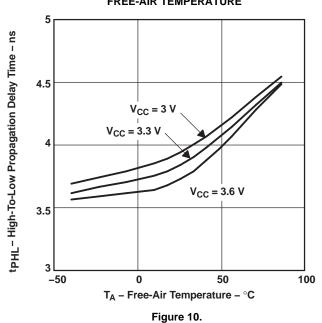
LOW-TO-HIGH PROPAGATION DELAY TIME vs FREE-AIR TEMPERATURE



HIGH-LEVEL OUTPUT VOLTAGE VS HIGH-LEVEL OUTPUT CURRENT



HIGH-TO-LOW PROPAGATION DELAY TIME vs FREE-AIR TEMPERATURE





TYPICAL CHARACTERISTICS (continued)

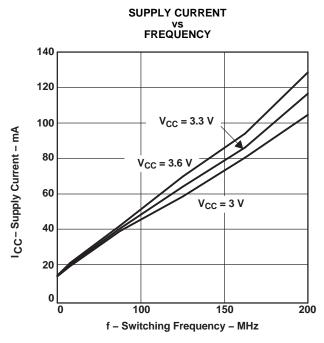
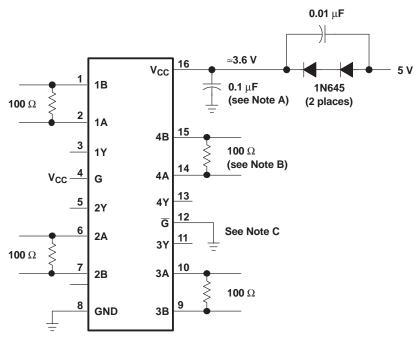


Figure 11.



APPLICATION INFORMATION



- A. Place a 0.1-µF Z5U ceramic, mica or polystyrene dielectric, 0805 size, chip capacitor between V_{CC} and the ground plane. The capacitor should be located as close as possible to the device terminals.
- B. The termination resistance value should match the nominal characteristic impedance of the transmission media with ±10%.
- C. Unused enable inputs should be tied to V_{CC} or GND as appropriate.

Figure 12. Operation with 5-V Supply

RELATED INFORMATION

IBIS modeling is available for this device. contact the local TI sales office or the TI Web site at www.ti.com for more information.

For more application guidelines, see the following documents:

- Low-Voltage Differential Signaling Design Notes (SLLA014)
- Interface Circuits for TIA/EIA-644 (LVDS) (SLLA038)
- Reducing EMI With LVDS (SLLA030)
- Slew Rate Control of LVDS Circuits (SLLA034)
- Using an LVDS Receiver With RS-422 Data (SLLA031)
- Evaluating the LVDS EVM (SLLA033)

TERMINATED FAILSAFE

A differential line receiver commonly has a fail-safe circuit to prevent it from switching on input noise. Current LVDS fail-safe solutions require either external components with subsequent reduction in signal quality or integrated solutions with limited application. This family of receivers has a new integrated fail-safe that solves the limitations seen in present solutions. A detailed theory of operation is presented in application note *The Active Fail-Safe Feature of the SN65LVDS32A* (SLLA082).

Figure 13 shows one receiver channel with active fail-safe. It consists of a main receiver that can respond to a high-speed input differential signal. Also connected to the input pair are two fail-safe receivers that form a window comparator. The window comparator has a much slower response than the main receiver and detects when the input differential falls below 80 mV. A 600-ns fail-safe timer filters the window comparator outputs. When fail-safe is asserted, the fail-safe logic drives the main receiver output to logic high.



APPLICATION INFORMATION (continued)

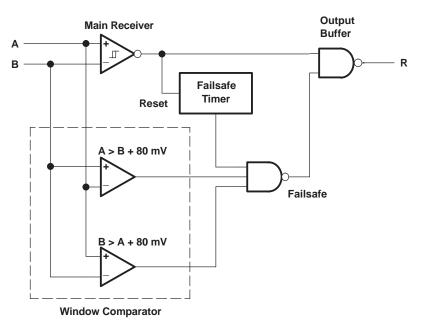


Figure 13. Receiver With Terminated Failsafe

ECL/PECL-to-LVTTL CONVERSION WITH TI'S LVDS RECEIVER

The various versions of emitter-coupled logic (i.e., ECL, PECL and LVPECL) are often the physical layer of choice for system designers. Designers know of the established technology and that it is capable of high-speed data transmission. In the past, system requirements often forced the selection of ECL. Now technologies like LVDS provide designers with another alternative. While the total exchange of ECL for LVDS may not be a design option, designers have been able to take advantage of LVDS by implementing a small resistor divider network at the input of the LVDS receiver. TI has taken the next step by introducing a wide common-mode LVDS receiver (no divider network required) which can be connected directly to an ECL driver with only the termination bias voltage required for ECL termination ($V_{\rm CC}$ –2 V).

Figure 14 and Figure 15 show the use of an LV/PECL driver driving 5 meters of CAT-5 cable and being received by Tl's wide common-mode receiver and the resulting eye pattern. The values for R3 are required in order to provide a resistor path to ground for the LV/PECL driver. With no resistor divider, R1 simply needs to match the characteristic load impedance of $50~\Omega$. The R2 resistor is a small value and is intended to minimize any possible common-mode current reflections.

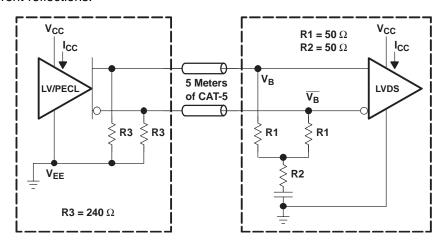


Figure 14. LVPECL or PECL to Remote Wide Common-Mode LVDS Receiver



APPLICATION INFORMATION (continued)

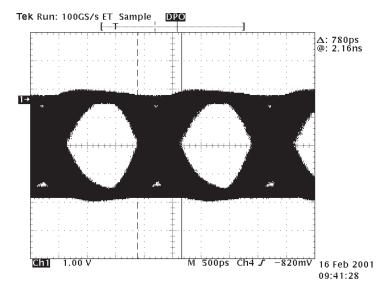


Figure 15. LV/PECL to Remote SN65LVDS32B at 500 Mbps Receiver Output (CH1)

TEST CONDITIONS

- V_{CC} = 3.3 V
- T_A = 25°C (ambient temperature)
- All four channels switching simultaneously with NRZ data. Scope is pulse-triggered simultaneously with NRZ data.

EQUIPMENT

- Tektronix PS25216 programmable power supply
- Tektronix HFS 9003 stimulus system
- Tektronix TDS 784D 4-channel digital phosphor oscilloscope DPO

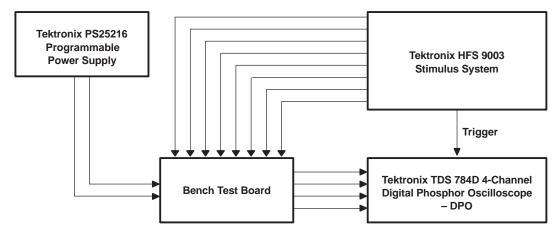


Figure 16. Equipment Setup





APPLICATION INFORMATION (continued)

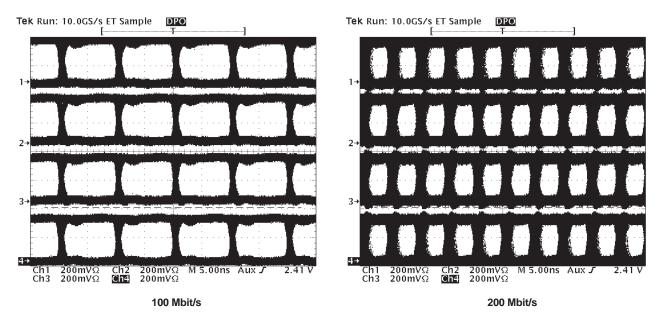


Figure 17. Typical Eye Pattern SN65LVDS32B



PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	e Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp (3)
SN65LVDS32BD	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN65LVDS32BDG4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN65LVDS32BDR	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN65LVDS32BDRG4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN65LVDS3486BD	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN65LVDS3486BDG4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN65LVDS3486BDR	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN65LVDS3486BDRG4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN65LVDS9637BD	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	Call TI	Level-1-260C-UNLIM
SN65LVDS9637BDG4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	Call TI	Level-1-260C-UNLIM
SN65LVDS9637BDR	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN65LVDS9637BDRG4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN65LVDT32BD	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN65LVDT32BDG4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN65LVDT32BDR	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN65LVDT32BDRG4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN65LVDT3486BD	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN65LVDT3486BDG4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN65LVDT3486BDR	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN65LVDT9637BD	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN65LVDT9637BDG4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN65LVDT9637BDR	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN65LVDT9637BDRG4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SNLVDT3486BDRG4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM

 $^{^{(1)}}$ The marketing status values are defined as follows:



PACKAGE OPTION ADDENDUM

17-Apr-2008

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

Important Information and Disclaimer: The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

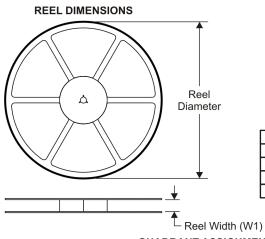
In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

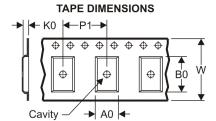




16-Apr-2008

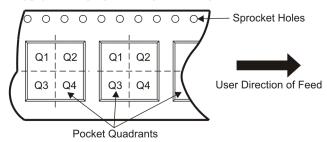
TAPE AND REEL INFORMATION





		Dimension designed to accommodate the component width
I	B0	Dimension designed to accommodate the component length
	K0	Dimension designed to accommodate the component thickness
	W	Overall width of the carrier tape
-	P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN65LVDS32BDR	SOIC	D	16	2500	330.0	16.4	6.5	10.3	2.1	8.0	16.0	Q1
SN65LVDS3486BDR	SOIC	D	16	2500	330.0	16.4	6.5	10.3	2.1	8.0	16.0	Q1
SN65LVDS9637BDR	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
SN65LVDS9637BDR	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
SN65LVDT32BDR	SOIC	D	16	2500	330.0	16.4	6.5	10.3	2.1	8.0	16.0	Q1
SN65LVDT3486BDR	SOIC	D	16	2500	330.0	16.4	6.5	10.3	2.1	8.0	16.0	Q1
SN65LVDT9637BDR	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1





*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN65LVDS32BDR	SOIC	D	16	2500	333.2	345.9	28.6
SN65LVDS3486BDR	SOIC	D	16	2500	346.0	346.0	33.0
SN65LVDS9637BDR	SOIC	D	8	2500	340.5	338.1	20.6
SN65LVDS9637BDR	SOIC	D	8	2500	346.0	346.0	29.0
SN65LVDT32BDR	SOIC	D	16	2500	346.0	346.0	33.0
SN65LVDT3486BDR	SOIC	D	16	2500	346.0	346.0	33.0
SN65LVDT9637BDR	SOIC	D	8	2500	346.0	346.0	29.0

IMPORTANT NOTICE

Texas Instruments Incorporated and its subsidiaries (TI) reserve the right to make corrections, modifications, enhancements, improvements, and other changes to its products and services at any time and to discontinue any product or service without notice. Customers should obtain the latest relevant information before placing orders and should verify that such information is current and complete. All products are sold subject to TI's terms and conditions of sale supplied at the time of order acknowledgment.

TI warrants performance of its hardware products to the specifications applicable at the time of sale in accordance with TI's standard warranty. Testing and other quality control techniques are used to the extent TI deems necessary to support this warranty. Except where mandated by government requirements, testing of all parameters of each product is not necessarily performed.

TI assumes no liability for applications assistance or customer product design. Customers are responsible for their products and applications using TI components. To minimize the risks associated with customer products and applications, customers should provide adequate design and operating safeguards.

TI does not warrant or represent that any license, either express or implied, is granted under any TI patent right, copyright, mask work right, or other TI intellectual property right relating to any combination, machine, or process in which TI products or services are used. Information published by TI regarding third-party products or services does not constitute a license from TI to use such products or services or a warranty or endorsement thereof. Use of such information may require a license from a third party under the patents or other intellectual property of the third party, or a license from TI under the patents or other intellectual property of TI.

Reproduction of TI information in TI data books or data sheets is permissible only if reproduction is without alteration and is accompanied by all associated warranties, conditions, limitations, and notices. Reproduction of this information with alteration is an unfair and deceptive business practice. TI is not responsible or liable for such altered documentation. Information of third parties may be subject to additional restrictions

Resale of TI products or services with statements different from or beyond the parameters stated by TI for that product or service voids all express and any implied warranties for the associated TI product or service and is an unfair and deceptive business practice. TI is not responsible or liable for any such statements.

TI products are not authorized for use in safety-critical applications (such as life support) where a failure of the TI product would reasonably be expected to cause severe personal injury or death, unless officers of the parties have executed an agreement specifically governing such use. Buyers represent that they have all necessary expertise in the safety and regulatory ramifications of their applications, and acknowledge and agree that they are solely responsible for all legal, regulatory and safety-related requirements concerning their products and any use of TI products in such safety-critical applications, notwithstanding any applications-related information or support that may be provided by TI. Further, Buyers must fully indemnify TI and its representatives against any damages arising out of the use of TI products in such safety-critical applications.

TI products are neither designed nor intended for use in military/aerospace applications or environments unless the TI products are specifically designated by TI as military-grade or "enhanced plastic." Only products designated by TI as military-grade meet military specifications. Buyers acknowledge and agree that any such use of TI products which TI has not designated as military-grade is solely at the Buyer's risk, and that they are solely responsible for compliance with all legal and regulatory requirements in connection with such use.

TI products are neither designed nor intended for use in automotive applications or environments unless the specific TI products are designated by TI as compliant with ISO/TS 16949 requirements. Buyers acknowledge and agree that, if they use any non-designated products in automotive applications, TI will not be responsible for any failure to meet such requirements.

Following are URLs where you can obtain information on other Texas Instruments products and application solutions:

Products Amplifiers amplifier.ti.com Data Converters dataconverter.ti.com DSP dsp.ti.com Clocks and Timers www.ti.com/clocks Interface interface.ti.com Logic logic.ti.com Power Mgmt power.ti.com microcontroller.ti.com Microcontrollers www.ti-rfid.com RF/IF and ZigBee® Solutions www.ti.com/lprf

Applications	
Audio	www.ti.com/audio
Automotive	www.ti.com/automotive
Broadband	www.ti.com/broadband
Digital Control	www.ti.com/digitalcontrol
Medical	www.ti.com/medical
Military	www.ti.com/military
Optical Networking	www.ti.com/opticalnetwork
Security	www.ti.com/security
Telephony	www.ti.com/telephony
Video & Imaging	www.ti.com/video
Wireless	www.ti.com/wireless

Mailing Address: Texas Instruments, Post Office Box 655303, Dallas, Texas 75265 Copyright © 2008, Texas Instruments Incorporated